

Title (en)
COMPUTER COOLING

Title (de)
COMPUTERKÜHLUNG

Title (fr)
REFROIDISSEMENT POUR ORDINATEUR

Publication
EP 4335257 A1 20240313 (EN)

Application
EP 22720133 A 20220406

Priority

- US 202163183259 P 20210503
- US 202117361064 A 20210628
- US 2022023572 W 20220406

Abstract (en)
[origin: WO2022235368A1] The description relates to cooling electronic components, such as computing devices. One example includes a rack defining a volume and multiple sealed chassis modules removably fluidly coupled to a two-phase condenser tank via a vapor coupler and a liquid coupler. Individual sealed chassis modules can contain one or more electronic components immersed in two-phase coolant that when heated by operation of the electronic components experiences a phase change from a liquid phase to a gas phase and travels to the two-phase condenser tank via the vapor coupler and is cooled in the two-phase condenser tank until experiencing a phase change back into the liquid phase. Individual sealed chassis modules can be decoupled from the two-phase condenser tank without releasing two-phase coolant and an entirety of the multiple sealed chassis modules and the condenser tank are contained in the volume of the rack.

IPC 8 full level
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CPC (source: EP)
H05K 7/203 (2013.01); **H05K 7/20809** (2013.01)

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